

Innovative **Technology** for a **Connected** World



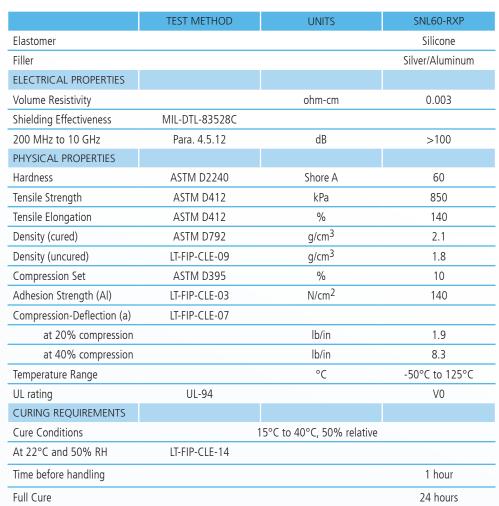


A rapid cure, silver/aluminum-filled silicone elastomer Form-In-Place gasket material.

Laird Technologies introduces its newest line of FIP products—EMI Sentry. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength

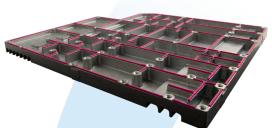
Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for basestations, PDAs, PC cards, radios, mobile phones, as well as many other cast or plastic enclosures and packaged electronic assemblies.

TYPICAL VALUES



(a) Compression-deflection bead size 0.60 mm (H) x 0.75 mm (W)

rev. 07/02/09



 does not represent actual color

global solutions: local support ™

USA: +1 866 928.8181 Europe: +49 8031.2460.0 Asia: +86 755.2714.1166





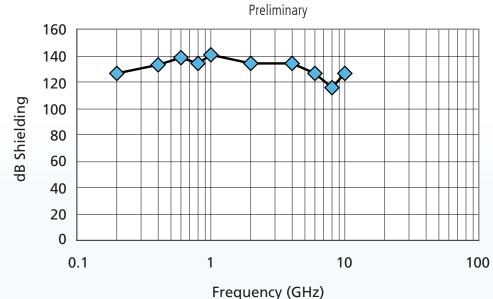


SNL60-RXP Form-In-Place

A rapid cure, silver/aluminum-filled silicone elastomer Form-In-Place gasket material.

SNL60-RXP is one of the new products in the EMI Sentry line. This paste has dynamic shielding effectiveness, strength for environmental protection, and is a room temperature-cured paste. Products in the EMI Sentry line all have superior adhesion strength, strong reliability in low compression sets, as well as heat and humidity resistance.

SNL60-RXP Shielding Effectiveness (dB)







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